

Ceramic thin film chip filter for packaging and testing technology

Ceramic thin film chip series

Currently, we have developed nearly 150 ceramic thin-film chip filter products, covering a frequency range of 2. Detailed information can be found in the list and specifications. We can provide quick response and supply within about two weeks. Additionally, we can customize and develop chips according to new user requirements, offering various types of filters such as bandpass, lowpass, highpass, and bandstop, as well as meeting various bandwidth requirements. Delivery can be completed within two to four weeks.

1. Characteristics and applications

特 点	应 用
● 薄膜工艺、精确仿真	微波通讯 电子对抗 雷达 导航 航空航天等 各种微波射频组件系统
● 频率范围：2GHz-60GHz	
● 结构型式：集总参数和分布参数	
● 滤波类型：带通、低通、高通、带阻	
● 响应函数：切比雪夫及广义切比雪夫等	
● 3dB 带宽：5%-100%	
● 阶数：2-13 阶	
● 接口形式：50 欧姆带线入出	
● 适合：微组装键合，多芯片集成模块	
● 工作温度：-55~+85℃	

(Note: Customization is available according to specific user)

2. Performance list

Bandpass series

序号	型号	频率范围 (GHz)	损耗 (dB)	带外抑制 (dBc)	外形尺寸 (mm)	页码
1	NBP1R85HR2-T7M9	1.75~1.95	≤3.5	≥75@1.2GHz ≥75@3.6GHz	6.5×9.5×0.39	P8
2	NBP2UR2-T7M11	1.9~2.1	≤3.5	≥60@1.0GHz ≥60@3.0GHz	7.0×10.8×0.39	P9
3	NBP2R4UR2-T7M10	2.4~2.5	≤3.5	≥75@1.2GHz ≥75@3.6GHz	7.0×9.5×0.39	P10
4	NBP2R6UR2-T7M9	2.5~2.6	≤3.5	≥60@1.3GHz ≥60@3.9GHz	7.0×9.0×0.39	P11
5	NMWBP2R9U0R6-T8M8	2.6~3.2	≤2.0	≥55@1.5GHz ≥25@4.0GHz	8.0×7.8×0.39	P12
6	NBP3R6UR2-T7M8	3.5~3.7	≤3.6	≥60@4.8GHz ≥60@2.4GHz	7.0×7.5×0.39	P13

7	NBP3R05TR5-T11M7	2.8~3.3	≤4.8	≥35@2.15GHz ≥45@4.2GHz	10.5×6.5×0.39	P14
8	NBP3R67UR3-T6M8	3.62~3.72	≤3.0	≥20@3.1GHz ≥25@4.15GHz	6.0×7.8×0.39	P15
9	NMWBP4R1U0R4-T8M6	3.85~4.25	≤2.0	≥45@3.0GHz ≥45@5.0GHz	8.0×5.5×0.39	P16
10	NMWBP4R5UR2-T8M5	4.4~4.65	≤4.5	≥40@3.9GHz ≥40@5.1GHz	8.0×5.5×0.26	P17
11	NMWBP4650H500-T9M8	4.4~4.9	≤0.9	≥20@2.0GHz ≥20@7.5GHz	9.0×8.0×0.39	P18
12	NMWBP4700H600-T9M5	4.4~5.0	≤3.0	≥48@3.5GHz ≥50@5.9GHz	9.0×5.5×0.39	P19
13	NMWBP4700U600-T11M5	4.4~5.0	≤3.0	≥40@4.025GHz ≥40@5.36GHz	11.0×5.5×0.39	P20
14	NMWBP5UR4-T8M5	4.8~5.2	≤4.5	≥40@4.3GHz ≥40@5.7GHz	8.0×5.5×0.26	P21
15	NBP5R16UR2-T14M6	5.05~5.26	≤5.6	≥50@4.56GHz ≥50@5.76GHz	14.0×5.5×0.26	P22
16	NBP5R65UR5-T6M6	5.425~5.9	≤3.0	≥70@3.0GHz ≥65@8.0GHz	6.0×6.0×0.26	P23
17	NMWBP5850U620-T11M5	5.54~6.16	≤4.0	≥45@5.0GHz ≥45@6.7GHz	11.0×5.5×0.26	P24
18	NBP6UR4-T7M6	6.2~6.6	≤3.0	≥50@4.0GHz ≥50@8.0GHz	7.0×6.0×0.26	P25
19	NMWBP6000U550-T9R0	5.72~6.27	≤3.0	≥55@5.0GHz ≥55@6.975GHz	9.0×5.5×0.26	P26
20	NMWBP6111U622-T11M5	5.8~6.422	≤4.0	≥40@5.46GHz ≥40@6.816GHz	11.0×5.5×0.26	P27
21	NMWBP6200U600-T9M5	5.9~6.5	≤3.5	≥50@5.0GHz ≥50@8.0GHz	9.0×5.5×0.26	P28
22	NMWBP6200H600-T9M5	5.9~6.5	≤2.1	≥40@5.0GHz ≥45@13.45GHz	9.0×5.5×0.26	P29
23	NMWBP6R28H0R87-T9M5	5.85~6.725	≤3.5	≥36@5.0GHz ≥50@8.0GHz	9.0×5.5×0.26	P30
24	NMWBP6R3UR6-T7M4	6.0~6.6	≤4.0	≥50@5.4GHz ≥40@7.1GHz	7.8×4.5×0.26	P31
25	NMWBP6586U328-T8M5	6.422~6.75	≤4.0	≥40@5.7GHz ≥35@7.1GHz	8.0×5.5×0.26	P32
26	NMWBP6850H620-T11M5	6.54~7.16	≤4.0	≥50@5GHz ≥50@7.7GHz	11.0×5.5×0.26	P33
27	NBP6R925UR25-T10M5	6.8~7.05	≤3.5	≥50@5.8GHz ≥35@8.0GHz	10.0×5.5×0.26	P34
28	NMWBP7H4-T5M6	4.9~9.1	≤2.0	≥20@12~15GHz	4.5×5.5×0.39	P35
29	NMWBP7R1UR4-T7M4	6.94~7.35	≤5.0	≥40@6.45GHz ≥40@7.9GHz	7.8×4.5×0.26	P36
30	NMWBP7300U800-T5R5	6.9~7.7	≤2.5	≥40@5.0GHz ≥40@9.45GHz	5.5×4.8×0.26	P37
31	NMWBP8R25U1R5-T8M4	7.5~9.0	≤2.0	≥50@6.5GHz ≥50@11GHz	8.0×4.5×0.26	P38

32	NBP8R4H1R3-T6M4	7.8~9.1	≤2.0	≥35@6.0GHz ≥35@12GHz	6.0×4.5×0.26	P39
33	NMWBP8800U800-T5R5	8.4~9.2	≤2.5	≥40@6.5GHz ≥40@10.95GHz	5.5×4.0×0.26	P40
34	NMWBP8R9U1R1-T5R5	8.35~9.45	≤2.5	≥40@6.725GHz ≥40@10.9GHz	5.5×4.0×0.26	P41
35	NBP9R475U1R2-T8M4	8.87~10.07	≤3.5	≥30@8.2GHz ≥40@10.8GHz	7.5×4.0×0.26	P42
36	NBP9R6U2-T7M4	8.6~10.6	≤3.5	≥40@7.3GHz ≥40@11.8GHz	6.5×4.0×0.26	P43
37	NMWBP9R6U1R2-T9M4	9.0~11.2	≤4.0	≥30@8.4GHz ≥30@10.8GHz	9.0×4.0×0.26	P44
38	NMWBP9R6U1R6-T9M4	8.8~10.4	≤2.5	≥30@6.4GHz ≥30@11.2GHz	9.0×4.0×0.26	P45
39	NBP9R6UR8-T7M4	9.2~10.0	≤4.5	≥50@8.0GHz ≥10@10.44GHz	6.5×4.0×0.26	P46
40	NBP9R6UR4-T8M4	9.39~9.81	≤5.5	≥30@10.44GHz	8.0×4.0×0.26	P47
41	NBP9R6UR2-T9M4	9.49~9.70	≤6.5	≥10@10.02GHz	9.0×4.0×0.26	P48
42	NMWBP9950U2300-T7M4	8.8~11.1	≤3.5	≥40@7.0GHz ≥25@12.0GHz	7.0×4.0×0.26	P49
43	NMWBP10050U4200-T8M4	7.95~12.15	≤1.8	≥40@6.7GHz ≥40@13.6GHz	8.0×4.0×0.26	P50
44	NMWBP11R2U1-T8M4	10.7~11.7	≤3.5	≥50@9.0GHz ≥40@12.4GHz	8.0×3.8×0.26	P51
45	NBP11R25U0R9-T10M4	10.7~11.8	≤3.5	≥60@9.35GHz	10.0×4.0×0.26	P52
46	NMWBP11R32UR75-T10M4	10.95~11.7	≤3.5	≥35@8.8GHz ≥50@9.55GHz	10.4×4.0×0.26	P53
47	NBP11R3U1-T6M4	10.85~11.8	≤3.5	≥65@5.9GHz ≥60@9.0GHz	5.5×3.5×0.26	P54
48	NMWBP11R65U2R3-T4M3	10.5~12.8	≤2.0	≥15@13.75GHz ≥40@15.0GHz	4.0×3.0×0.26	P55
49	NMWBP11R72U2R1-T5M4	10.7~12.75	≤2.5	≥30@9.0GHz ≥30@13.75GHz	5.0×3.5×0.26	P56
50	NMWBP11R72U2R1-T8M4	10.7~12.75	≤3.2	≥63@6.55GHz ≥40@9.0GHz	8.0×4.0×0.26	P57
51	NMWBP11750U2100-T19R8	10.7~12.8	≤2.0	≥40@8.0GHz ≥40@16.0GHz	19.8×4.6×0.26	P58
52	NMWBP12R1U1R3-T8M4	11.45~12.75	≤3.2	≥50@10.0GHz ≥50@13.75GHz	8.0×3.8×0.26	P59
53	NBP12R25U0R9-T10M4	11.7~12.8	≤3.5	≥60@10.35GHz	10.0×4.0×0.26	P60
54	NMWBP12R3UR4-T10M4	12.1~12.5	≤4.5	≥65@11.2GHz ≥40@13.2GHz	10.0×4.0×0.26	P61
55	NMWBP12R5U2-T7M3	11.5~13.5	≤2.5	≥40@9.6GHz ≥40@15GHz	7.0×3.0×0.26	P62
56	NMWBP12R5UR5-T9M4	12.25~12.75	≤3.5	≥50@9.7GHz ≥50@10.35GHz	9.0×4.0×0.26	P63

57	NMWBP12R8UR4-T10M4	12.6~13.0	≤4.5	≥65@11.2GHz ≥50@14.0GHz	10.0×4.0×0.26	P64
58	NMWBP13R1U3R4-T6M3	11.4~14.8	≤2.0	≥40@9.0GHz ≥40@16.5GHz	6.0×3.0×0.26	P65
59	NMWBP13R8U1R6-T8M3	13.0~14.6	≤3.0	≥40@11.6GHz ≥40@16.0GHz	8.0×3.2×0.26	P66
60	NMWBP14R12H0R75-T6M3	13.75~14.5	≤2.5	≥45@11.5GHz ≥45@16.0GHz	6.2×3.0×0.26	P67
61	NMWBP14125H750-T6M3	13.75~14.5	≤2.5	≥45@11.5GHz ≥45@16.0GHz	6.2×3.0×0.26	P68
62	NMWBP14125H750-T8M3	13.75~14.5	≤2.8	≥40@12.75GHz	8.0×3.0×0.26	P69
63	NMWBP14R5U2-T7M3	13.5~15.5	≤2.8	≥40@12.4GHz ≥40@17.2GHz	6.5×3.0×0.26	P70
64	NMWBP14650U4300-T7M3	12.5~16.8	≤2.0	≥30@8.4GHz ≥30@18.25GHz	7.0×2.8×0.26	P71
65	NMWBP14R65U2R6-T7M3	13.35~15.95	≤2.5	≥55@10.0GHz ≥55@19.0GHz	7.0×3.2×0.26	P72
66	NMWBP14650U300-T6R0	14.5~14.8	≤3.5	≥25@13.05GHz ≥25@15.8GHz	6.0×2.9×0.26	P73
67	NMWBP14R65U0R3-T7M4	14.5~14.8	≤4.8	≥25@15.35GHz ≥20@29.0GHz	6.5×4.0×0.26	P74
68	NBP14R7UR4-T7M3	14.5~14.9	≤3.5	≥55@12.0GHz ≥55@18.2GHz	7.0×3.0×0.26	P75
69	NMWBP14925H850-T7M4	14.5~15.35	≤2.5	≥35@12.9GHz ≥20@13.5GHz	7.5×4.0×0.26	P76
70	NMWBP14R925U0R85-T9M4	14.5~15.35	≤4.2	≥40@13.7GHz ≥15@14.16GHz	9.0×4.0×0.26	P77
71	NMWBP15U2-T8M3	14.0~16.0	≤2.5	≥40@12.8GHz ≥40@17.2GHz	7.5×2.8×0.26	P78
72	NMWBP15H1-T7M3	14.5~15.5	≤2.5	≥55@12.2GHz ≥30@16.8GHz	7.2×3.0×0.26	P79
73	NMWBP15000H1000-T8M3	14.5~15.5	≤2.5	≥55@12.2GHz ≥30@14.2GHz	8.0×3.0×0.26	P80
74	NMWBP15H0R2-T7M3	14.9~15.1	≤2.5	≥55@12.2GHz ≥35@16.8GHz	6.5×3.0×0.26	P81
75	NMWBP15R2U0R3-T7M4	15.05~15.35	≤4.8	≥24@14.8GHz ≥20@30.7GHz	6.5×4.0×0.26	P82
76	NMWBP15200U300-T6R0	15.05~15.35	≤3.5	≥24@14.8GHz ≥20@30.1GHz	6.0×2.7×0.26	P83
77	NMWBP15R4U1R6-T8M3	14.6~16.2	≤3.0	≥40@13.2GHz ≥40@17.5GHz	8.0×3.2×0.26	P84
78	NMWBP15850U3700-T10R0	14.0~17.7	≤2.5	≥40@12.4GHz ≥30@18.8GHz	10.0×2.8×0.26	P85
79	NMWBP15950U3300-T10R4	14.3~17.6	≤2.0	≥40@8.0GHz ≥40@24.0GHz	10.5×2.6×0.26	P86
80	NMWBP16U8-T6M2	12.0~20.0	≤2.0	≥33@10.0GHz ≥25@22.0GHz	6.0×2.2×0.26	P87
81	NMWBP16U4R0-T8M3	14.0~18.0	≤2.0	≥40@12.5GHz ≥40@20.5GHz	7.5×2.8×0.26	P88

82	NMWBP17U2R0-T6M3	16.0~18.0	≤2.5	≥40@14.5GHz ≥40@19.5GHz	6.0×2.5×0.26	P89
83	NMWBP17R4U4R8-T6M2	15.0~19.8	≤2.0	≥40@12.0GHz ≥40@22.2GHz	6.0×2.2×0.26	P90
84	NNBP17R8U0R2-T7M3	17.7~17.9	≤3.5	≥60@15.5GHz	7.0×2.8×0.26	P91
85	NBP18R5U1R6-T7M3	17.7~19.3	≤2.0	≥70@13.3GHz	7.0×2.8×0.26	P92
86	NMWBP18R7U2R0-T7M3	17.7~19.7	≤2.0	≥20@16.8GHz ≥20@20.6GHz	6.5×2.5×0.26	P93
87	NMWBP18R7U2R0-T10M3	17.7~19.7	≤4.0	≥40@16.8GHz ≥40@20.6GHz	10.0×2.5×0.26	P94
88	NMWBP19450U3500-T6M3	17.7~21.2	≤2.0	≥60@13.0GHz ≥40@24.0GHz	5.5×2.8×0.26	P95
89	NMWBP19450U3700-T9M3	17.6~21.3	≤3.0	≥48@15.2GHz	8.0×2.5×0.26	P96
90	NMWBP19450U3900-T4M3	17.5~21.4	≤3.0	≥40@31GHz ≥55@13.0GHz	4.0×2.5×0.26	P97
91	NBP19R5U1R6-T7M3	18.7~20.3	≤2.0	≥65@14.3GHz	7.0×2.8×0.26	P98
92	NMWBP19900U2800-T9M3	18.5~21.3	≤2.8	≥30@17.4GHz ≥50@28.0GHz	8.8×3.0×0.26	P99
93	NBP20R4U1R6-T7M3	19.6~21.2	≤2.0	≥65@15.2GHz	7.0×2.8×0.26	P100
94	NMWBP20750U2500-T7M2	19.5~22.0	≤2.8	≥50@16.2GHz ≥55@25.0GHz	7.0×2.5×0.26	P101
95	NMWBP22H1R0-T9M3	21.5~22.5	≤2.5	≥50@12.0GHz ≥20@23.8GHz	9.5×3.2×0.26	P102
96	NMWBP22000U1000-T9M3	21.5~22.5	≤2.5	≥50@12.0GHz ≥20@23.8GHz	9.5×3.2×0.26	P103
97	NMWBP22200U800-T11M3	21.8~22.6	≤4.0	≥50@20.0GHz ≥50@24.0GHz	11.0×3.0×0.26	P104
98	NMWBP22R6U3R4-T6M2	20.9~24.3	≤2.2	≥40@17.4GHz ≥40@26.7GHz	6.0×2.2×0.26	P105
99	NMWBP23000U800-T11M3	22.6~23.4	≤4.0	≥50@20.8GHz ≥50@24.8GHz	11.0×3.0×0.26	P106
100	NMWBP25U4-T8M2	23.0~27.0	≤2.5	≥40@20.5GHz ≥40@29.0GHz	8.0×2.0×0.26	P107
101	NMWBP25800U900-T9R5	25.5~26.13	≤3.5	≥45@22.85GHz ≥35@27.65GHz	9.5×3.5×0.26	P108
102	NBP26U2R2-T4M2	24.9~27.1	≤1.5	≥50@13.5GHz ≥45@37.0GHz	4.0×2.2×0.26	P109
103	NMWBP26800U1500-T9R5	26.13~27.5	≤3.2	≥45@23.5GHz ≥15@28.7GHz	9.5×3.5×0.26	P110
104	NMWBP28R1U1R2-T12M3	27.5~28.7	≤4.0	≥40@26.55GHz ≥35@29.65GHz	12.0×2.5×0.26	P111
105	NMWBP28300U1600-T9M2	27.5~29.1	≤4.0	≥55@25.1GHz ≥12@29.9GHz	8.8×2.3×0.26	P112
106	NBP28R3U1R6-T11M3	27.5~29.1	≤4.0	≥60@25.1GHz ≥65@32.3GHz	11.0×2.5×0.26	P113

107	NMWBP28400T2200-T10M3	27.3~29.5	≤3.2	≥45@24.45GHz ≥65@31.4GHz	10.5×3.0×0.26	P114
108	NMWBP28400U2600-T10M3	27.1~29.7	≤3.2	≥35@24.4GHz ≥5@30.4GHz	10.0×3.0×0.26	P115
109	NMWBP28R5U1R2-T12M3	27.9~29.1	≤4.0	≥40@26.95GHz ≥35@30.05GHz	12.0×2.5×0.26	P116
110	NMWBP29R2U4-T8M3	27.2~31.2	≤1.8	≥40@24.5GHz ≥40@34.9GHz	8.0×3.0×0.26	P117
111	NMWBP29200U1600-T9M2	28.4~30.0	≤4.0	≥55@26.0GHz ≥12@30.8GHz	8.8×2.3×0.26	P118
112	NBP29R2U1R6-T11M3	28.4~30.0	≤4.0	≥60@26.0GHz ≥65@33.2GHz	11.0×2.5×0.26	P119
113	NMWBP29250U3500-T15M3A	27.5~31.0	≤2.6	≥25@26.95GHz	15.0×3.0×0.26	P120
114	NMWBP29350U8500-T6M2	25.1~33.6	≤1.5	≥30@16.8GHz ≥55@37.5GHz	6.0×2.5×0.26	P121
115	NBP29R5U1R2-T11M3	28.9~30.1	≤5.5	≥30@28.3GHz ≥55@27.63GHz	11.0×3.2×0.26	P122
116	NMWBP30200U900-T9R5	29.35~31.05	≤3.0	≥20@32.0GHz	9.5×3.0×0.26	P123
117	NBP30R2U1R6-T11M3	29.4~31.0	≤4.0	≥60@27.0GHz ≥65@34.2GHz	11.0×2.5×0.26	P124
118	NMWBP30200U1600-T9M2	29.4~31.0	≤4.0	≥55@27.0GHz ≥12@31.8GHz	8.8×2.3×0.26	P125
119	NMWBP32U16-T8M2	24.0~40.0	≤2.0	≥10@22.0GHz ≥25@20.0GHz	8.0×1.9×0.26	P126
120	NMWBP33U4-T8M2	31.0~35.0	≤2.8	≥40@28.0GHz ≥30@38.0GHz	8.0×2.5×0.26	P127
121	NMWBP34R5U9-T8M2	30.0~39.0	≤1.5	≥40@27.0GHz ≥40@44.0GHz	8.0×1.9×0.26	P128
122	NMWBP35H4-T6M2	32.8~37.2	≤2.5	≥60@18.5GHz	6.0×2.2×0.26	P129
123	NMWBP35R3U5R6-T8M2	32.5~38.1	≤1.5	≥40@29.8GHz ≥40@42.1GHz	8.0×2.5×0.26	P130
124	NMWBP37U3-T8M2	35.5~38.5	≤2.8	≥40@33.0GHz ≥30@40.0GHz	8.0×2.5×0.26	P131
125	NMWBP40U3-T8M2	38.5~41.5	≤2.8	≥40@35.4GHz ≥30@44.0GHz	8.0×2.5×0.26	P132
126	NMWBP42U3-T8M2	40.5~43.5	≤2.8	≥40@37.4GHz ≥30@46.0GHz	8.0×2.5×0.26	P133
127	NMWBP45U3-T8M2	43.5~46.5	≤2.8	≥40@40.0GHz ≥30@50.0GHz	8.0×2.5×0.26	P134
128	NMWBP45U6-T7M2	42.0~48.0	≤2.0	≥40@37.0GHz ≥20@51.5GHz	8.0×2.5×0.26	P135
129	NMWBP48U3-T8M2	46.5~49.5	≤2.8	≥40@41.0GHz ≥30@53.5GHz	8.0×2.5×0.26	P136
130	NMWBP50U7-T7M2	46.5~53.5	≤2.0	≥40@40.5GHz	8.0×2.5×0.26	P137

Low-pass, high-pass, band-stop, etc.:

序号	型号	频率范围 (GHz)	损耗 (dB)	带外抑制 (dBc)	外形尺寸 (mm)	页码
131	NMWBR2R4/R1-T12M6 (带阻)	1.3~2.3	≤1.8	≥20 @2.4GHz	12.0×6.0×0.39	P138
132	NMWBR4R2/4R4-T22M11 (带阻)	4.2~4.4	≤2.0	≥30 @4.2~4.4GHz	22.0×11.0×0.39	P139
133	NMWBR4R84/5R15-T22M11 (带阻)	4.84~5.15	≤2.0	≥30 @4.84~5.15GHz	22.0×11.0×0.39	P140
134	NMWLPH4900-T9M8 (低通)	DC~4.9	≤0.6	≥20 @5.9~10.0GHz	9.0×8.0×0.39	P141
135	NMWLPU5000-T14M5 (低通)	DC~5.0	≤2.3	≥27 @6.4~10.0GHz	14.0×5.0×0.26	P142
136	NMWBR6R0/6R6-T22M11 (带阻)	6.0~6.6	≤2.0	≥30.0 @6.0~6.6GHz	22.0×11.0×0.39	P143
137	NMWLPU6800-T12M4 (低通)	DC~6.8	≤2.0	≥28 @9.2~14.0GHz	12.0×4.0×0.26	P144
138	NMWLPU9000-T12M3 (低通)	DC~9.0	≤2.0	≥28 @12.8~18.0GHz	12.0×3.5×0.26	P145
139	NMWLPU11000-T7M3 (低通)	DC~10.6	≤1.0	≥25 @20.8~21.2GHz	7.0×3.0×0.26	P146
140	NMWLPU12000-T9M3 (低通)	DC~10.6	≤0.5	≥25 @20.8~21.2GHz	9.0×3.0×0.26	P147
141	NHP13R75-T8M4 (高通)	13.75~14.5	≤0.65	≥25 @10.7~12.75GHz	8.0×4.0×0.80	P148
142	NHP13R75-T5M8 (高通)	13.75~14.5	≤0.65	≥25 @10.7~12.75GHz	4.5×8.0×0.80	P149
143	NMWLPU15000-T9M3 (低通)	DC~15.0	≤1.0	≥30 @23.0~35.0GHz	9.5×3.0×0.26	P150
144	NMWLPU18000-T9M3 (低通)	DC~18.0	≤1.0	≥20 @23.0~35.0GHz	9.5×3.0×0.26	P151
145	NMWLP26R0-T4M2 (低通)	DC~26.0	≤1.5	≥40 @33.9GHz	4.0×1.6×0.26	P152
146	NMWYS34.4/35.6T1-T14M3 (延时线)	34.4~35.6	≤3.2	$\Delta T=1.0 \pm 0.1ns$	14.0×3.0×0.26	P153

Performance Characteristics

High Q ceramic material

- Precise simulation, thin film technology
- Low temperature drift, high performance, miniaturization
- Gold wire bonding, suitable for multi-chip integrated modules

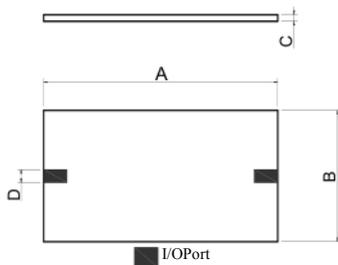
environmental parameters

工作温度	-55℃~+85℃
存储温度	-55℃~+125℃
最大输入功率	30dBm

电特性 (T_A=+25℃)

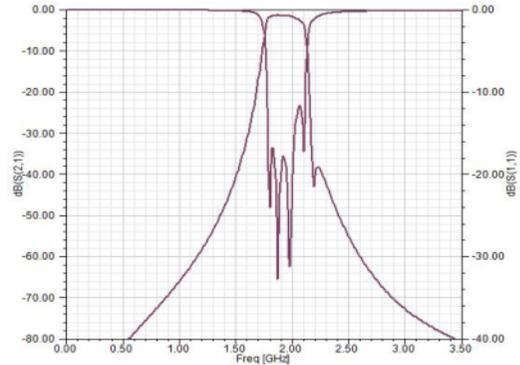
项目	规范值	单位
中心频率	1.85	GHz
通带频率	1.795~1.905	GHz
通带损耗	≤3.0	dB
驻波比	≤1.7	—
带外抑制	≥45@DC~1.2GHz	dBc
	≥50@2.6GHz	dBc
阻抗	50	Ω

Overall dimensions



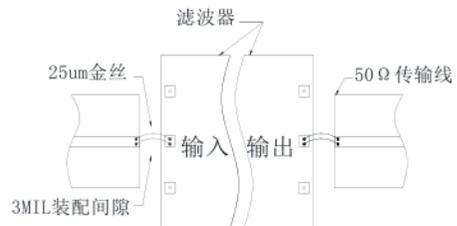
尺寸符号	最小值	公称值	最大值
A	6.4	—	6.5
B	8.9	—	9.0
C	—	0.39	—
D	—	0.06	—

typical curve



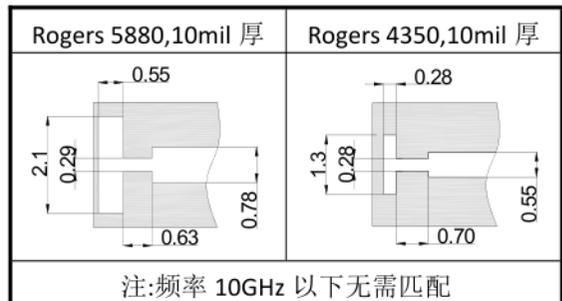
Instructions

1) Assembly suggestions



2) Precautions

- It is recommended to use the chip in separate cavities, with both sides 0.2mm away from the side walls. The inlet and outlet ports can be interchangeable, and the surface should be 3mm away from the upper cover;
- It is recommended to use low-stress conductive adhesive for bonding the chip;
- The chip should be mounted on a carrier with a thermal expansion coefficient comparable to that of the substrate, such as Kovar or molybdenum-copper, with a carrier thickness ≥;
- It is recommended to adopt a T-shaped matching at the bonding point, as follows:



- It is recommended to store in a nitrogen environment or a dry environment;
- If you have any questions, please contact us

Performance Characteristics

- High Q ceramic material
- Precise simulation, thin film technology
- Low temperature drift, high performance, miniaturization
- Gold wire bonding, suitable for multi-chip integrated modules

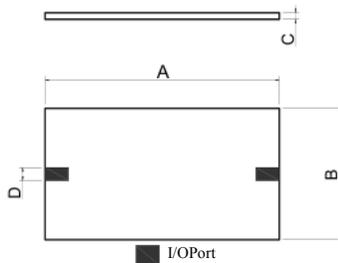
environmental parameters

工作温度	-55℃~+85℃
存储温度	-55℃~+125℃
最大输入功率	30dBm

电特性 (T_A=+25℃)

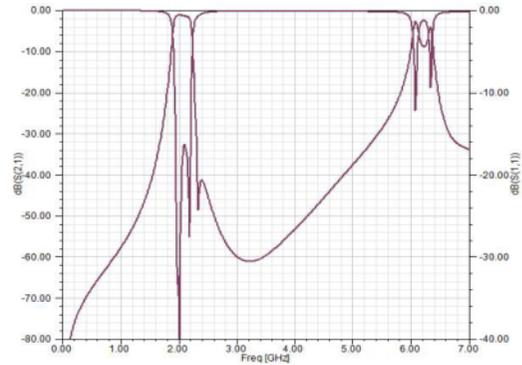
项目	规范值	单位
中心频率	2.0	GHz
通带频率	1.9~2.1	GHz
中心损耗	≤3.5	dB
驻波比	≤1.7	—
带外抑制	≥60@1.0GHz	dBc
	≥60@3.0GHz	dBc
阻抗	50	Ω

Overall dimensions



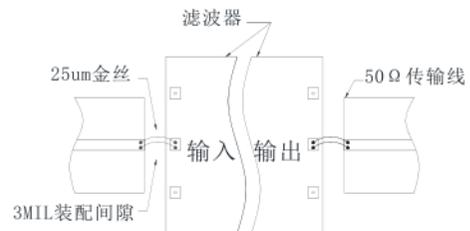
尺寸符号	最小值	公称值	最大值
A	6.9	—	7.0
B	10.7	—	10.8
C	—	0.39	—
D	—	0.06	—

typical curve



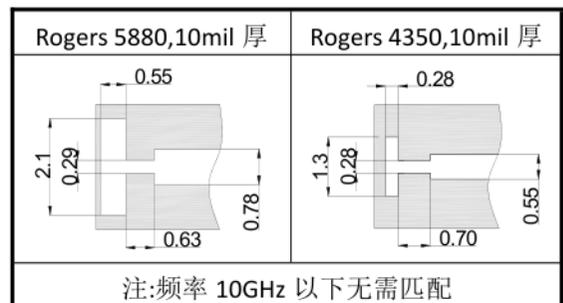
Instructions

1) Assembly suggestions



2) Precautions

- It is recommended to use the chip in separate cavities, with a distance of 0.2mm from both sides to the side wall, interchangeable inlet and outlet ports, and a distance of 3mm between the surface and the upper cover;
- It is recommended to use low-stress conductive adhesive for bonding the chip;
- The chip should be mounted on a carrier with a thermal expansion coefficient comparable to that of the substrate, such as Kovar or molybdenum-copper, with a carrier thickness ≥;
- It is recommended to adopt a T-shaped match at the bonding point, as follows:



- It is recommended to store in a nitrogen environment or a dry environment;
- If you have any questions, please contact us

Performance Characteristics

- High Q ceramic material
 - Precise simulation, thin film technology
- Low temperature drift, high performance, miniaturization
- Gold wire bonding, suitable for multi-chip integrated modules

environmental parameters

typical curve

Instructions

1) Assembly suggestions

2) Precautions

- a) It is recommended to use the chip in separate cavities, with both sides 0.2mm away from the side walls, interchangeable inlet and outlet ports, and a surface 3mm away from the upper cover;
- b) It is recommended to use low-stress conductive adhesive for bonding the chip;
- c) The chip should be mounted on a carrier with a thermal expansion coefficient comparable to that of the substrate, such as Kovar or molybdenum-copper, with a carrier thickness \geq ;
- d) It is recommended to adopt T-type matching at the bonding point, as follows:

Overall dimensions

I/OPort

e) It is recommended to store it in a nitrogen environment or a dry environment;

f) If you have any questions, please contact us

Performance Characteristics

High Q ceramic material

- Precise simulation, thin film technology

Low temperature drift, high performance,
miniaturization

Gold wire bonding, suitable for multi-chip integrated modules

environmental parameters

typical curve

Instructions

1) Assembly suggestions

2) Precautions

a) It is recommended to use the chip in separate chambers, with both sides 0.2mm away from the side walls. The inlet and outlet ports can be interchangeable, and the surface should be 3mm away from the upper cover;

b) It is recommended to use low-stress conductive adhesive for bonding the chip;

c) The chip should be mounted on a carrier with a thermal expansion coefficient comparable to that of the substrate, such as Kovar or molybdenum-copper, with a carrier thickness \geq ;

d) It is recommended to adopt a T-shaped matching at the bonding point, as follows:

Overall dimensions

I/OPort

e) It is recommended to store in a nitrogen environment or a dry environment;

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Performance Characteristics

- High Q ceramic material
- Precise simulation, thin film technology
- Low temperature drift, high performance, miniaturization
- Gold wire bonding, suitable for multi-chip integrated modules

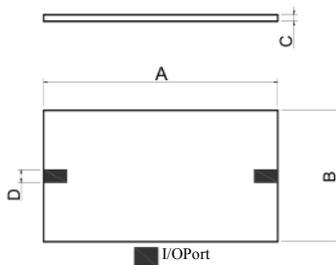
environmental parameters

工作温度	-55℃~+85℃
存储温度	-55℃~+125℃
最大输入功率	30dBm

电特性 (T_A=+25℃)

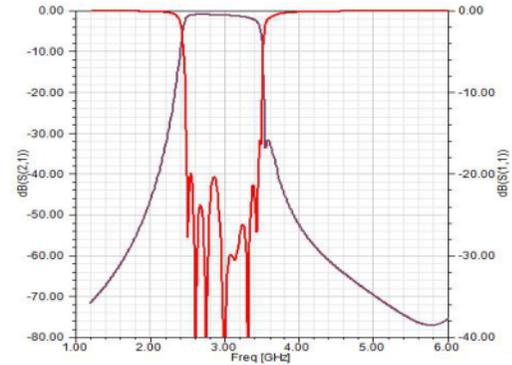
项目	规范值	单位
中心频率	2.9	GHz
通带频率	2.6~3.2	GHz
中心损耗	≤2.0	dB
驻波比	≤1.7	—
带外抑制	≥55@0.9~1.5GHz	dBc
	≥35@4.0GHz	dBc
阻抗	50	Ω

Overall dimensions



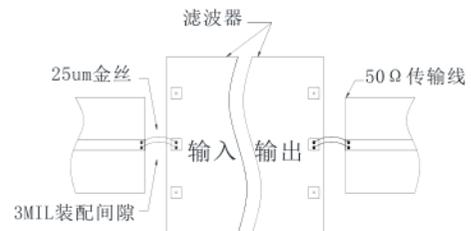
尺寸符号	最小值	公称值	最大值
A	7.9	—	8.0
B	7.7	—	7.8
C	—	0.39	—
D	—	0.20	—

typical curve



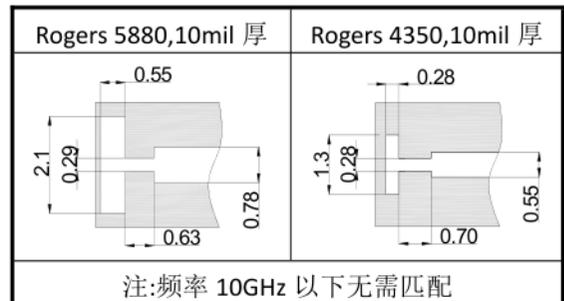
Instructions

1) Assembly suggestions



2) Precautions

- It is recommended to use the chip in separate cavities, with both sides 0.2mm away from the side walls. The inlet and outlet ports can be interchangeable, and the surface should be 3mm away from the upper cover;
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